

**P-Ch MOSFET** 

## **General Description**

The WST03P10 is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WST03P10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

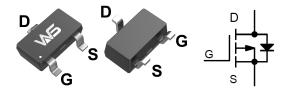
### **Product Summery**

BVDSS	RDSON	ID
-100V	300mΩ	-3A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter.
- Networking DC-DC Power System
- Load Switch

# **SOT-23-3L Pin Configuration**



#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	-100	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V	-3	А	
I <sub>DP</sub>	Pulsed Drain Current	-9	А	
P <sub>D</sub>	Total Power Dissipation	1.5	W	
TJ,TSTG	Operating Junction and Storage Temperature Range -55 to 150		$^{\circ}$	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient		125	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.03		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-3A		300	350	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-1A		320	450	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V V 1 050 A	-1.2	-1.9	-3.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$		4.56		mV/℃
	Drain Source Leakage Current	V <sub>DS</sub> =-100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-100V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-0.8A		3		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		16		Ω
$Q_{g}$	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-0.5A		4.5		
Q <sub>gs</sub>	Gate-Source Charge			1.14		nC
$Q_{gd}$	Gate-Drain Charge			1.5		
T <sub>d(on)</sub>	Turn-On Delay Time			17		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =-50V , V <sub>GS</sub> =-10V ,		2.8		
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=3.3\Omega$ , $R_L=2\Omega$		4.5		ns
T <sub>f</sub>	Fall Time			3.1		
C <sub>iss</sub>	Input Capacitance			550		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		56		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			35		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-3.0	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A			-1.2	V

#### Note:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- **4.** Guaranteed by design, not subject to production



# **Typical Characteristics**

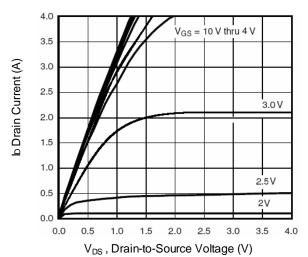


Fig.1 Typical Output Characteristics

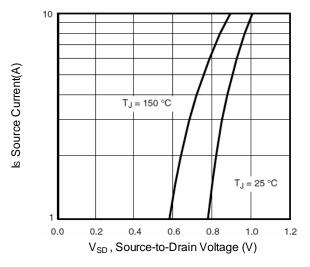


Fig.3 Forward Characteristics of Reverse

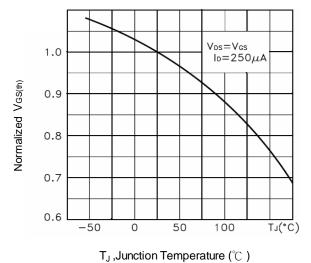


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

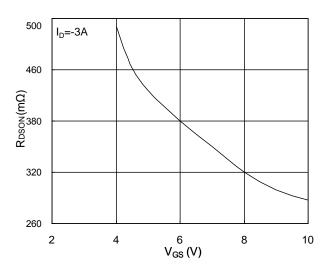


Fig.2 On-Resistance vs. Gate-Source

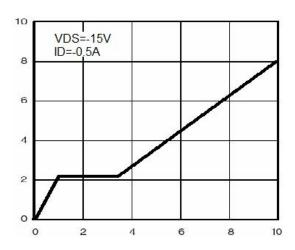


Fig.4 Gate-Charge Characteristics

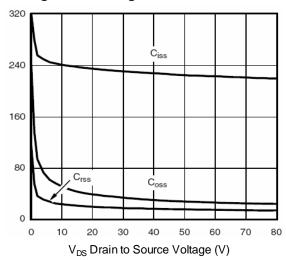


Fig.6 Capacitance



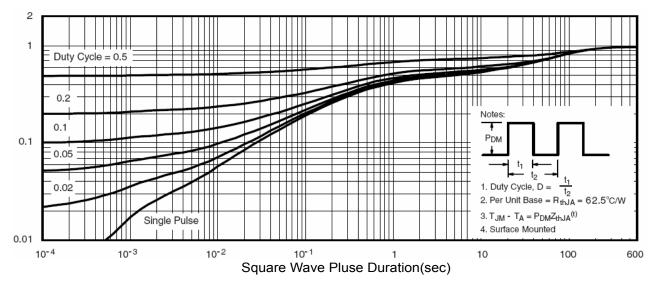
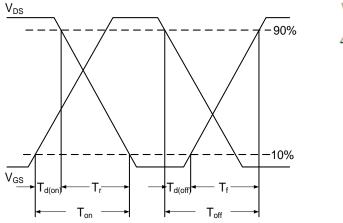


Fig.9 Normalized Maximum Transient Thermal Impedance



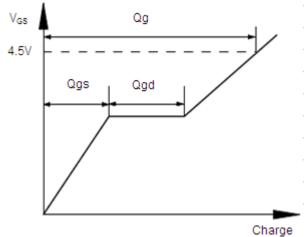


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform



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